

KRYLEX®

KRYLEX ELECTRONIC

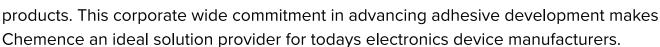
ASSEMBLY SOLUTIONS

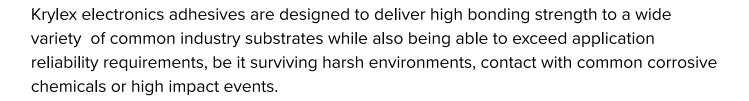


ELECTRONIC ASSEMBLY SOLUTIONS

Chemence, one of the leading global manufacturers of adhesives, sealants and resins for automotive, electronics, consumer, medical and industrial applications, has been setting new standards of performance for todays challenging bonding applications.

Krylex performance adhesives for consumer and Automotive electronics applications are formulated, using our long standing corporate expertise across a variety of product chemistries to deliver superior innovative





On occasions where innovation is required Chemence chemists are able to rapidly formulate bespoke products providing customers the ability to solve difficult assembly problems.

Chemence understand what is required to be an leading materials company in todays Electronics supply chain and our global team are available to exceed customer needs and requirements around the world.

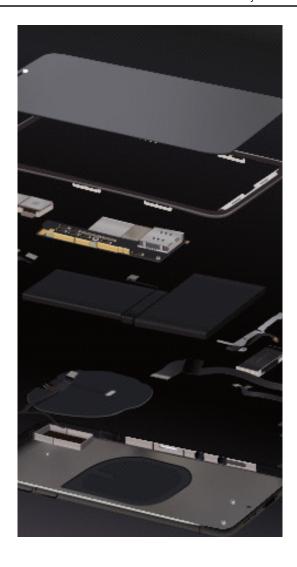




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UV ADHESIVE SOLUTION FOR GENERAL PURPOSE ELECTRONIC ASSEMBLY APPLICATIONS

Krylex UV or 'command cure', adhesives are formulated to react in the presence of the appropriate intensity of UV light. Krylex UV cure adhesives are designed to meet the unique challenges and requirements required in the assembly of electronic devices and components. The individual distinct products are formulated with specific application challenges in mind whether bonding too difficult to stick to plastics and metals or maximising UPH Efficiencies.

KRYLEX* UV Cure Adhesives Offer:

- · Rapid UV Cure fixation.
- · Exceptional depth of UV Penetration.
- · 100% Solids (No solvent) formulations
- · High adhesion too difficult to bond to plastics e.g., LCP (Liquid Crystal Polymer), PC, PA, etc....
- · High adhesion too difficult to bond to metals e.g., Anodised Al, ITO (Indium Tin Oxide), etc...
- · Excellent Reliability performance.
- · A wide range of rheology options for different application require ments.
- · UPH efficiencies.
- · Compliance with cyto-toxicity standards.
- · ROHS Compliant





Product	Description	Typical Application	Color	Viscosity CPS	[,] Hardness	Cure Condition	Shelf Life, months
KU5001T	High adhesion to metals and plastics / Good Depth of cure	Encapsulant	Translucent	4200	75 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12
KU5003	High adhesion to metals and plastics / High Impact strength	Gap filling and sealing	Clear - Amber	160	44 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12
KU5003T	Thixotropic version of KU5003	Structural Bonding, Encapsulation	Clear - Amber	1000	44D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12
KU5016	High Peel strength for flexible substrates/ Excellent adhesion to PA and PET / Tack free	Flexible substrate bonding - High Peel force bonds - wire fixing, flex circuit	Clear	4500	68 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12
KU5023	Higher peel strength than 5016 , tacky, low shrinkage - 'DispensiblePSA' (High tack after UV Exposure)	Flexible substrate bonding - High Peel force bonds - wire fixing, flex circuit	Clear	1500		365 -405nm LED 30 mW/cm2 , 2500 mJ	12
KU5026	Excellent cure speed - 2 second cure/ Excellent Adhesion to PC, LCP and other difficult to bond plastics/ Good Impact Performance	Lens to Barrel, General Purpose plastic to plastic and plastic to metal bonding	Translucent	9800	55 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12
KU5027	Soft/ Very High Elongation - High Impact strength	Lens to Barrell, High Impact Plastic Bonding	Translucent	12600	37 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12
KU5029	Medium softness and elongation (between KU5026 and KU5027)	Lens to Barrell, High Impact PlasticBonding	Translucent	10100	45 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12
KU5039A	High Tg ~115 ° C. Meets High temperature resistance (>120 ° C) and High temperature and heat humidity (85C/85%RH) requirements/ Good Adhesion to metals and plastics/ Good Impact and drop performance	Microspeaker/ High Temperature Performance applications	Translucent	6000	85 A	365 -405nm LED 30 mW/cm2 , 2500 mJ	12
KU5040	Excellent Temp Humid/ Excellent Adhesion to metals and plastics/ Good Impact and drop performance	Microspeaker/ High Temperature Performance applications	Translucent	4800	50 A	365 -405nm LED 30 mW/cm2 , 2500 mJ	12
KU5045	Fast cure, low shrinkage, Tack Free/ Good Adhesion to plastic substrates, metals and glass	Battery Pouch Seal/ Sealing	Black	7000	42 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	6
KU5144	low tack/ Excellent Adhesion to PET and Nylon and other plastic substrates	Battery Pouch Seal/ Sealing	Black	7000	54 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12
KU5145	Clear version of KU5144	Battery Pouch Seal/ Sealing	Clear	7400	51 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12
KU5146B	Fast Cure/ Optically Clear/ Good adhesion to plastic, metal and glass/ Good Abrasion and scratch resistance (Pencil hardness -6H)/ High Refractive index (1.56)/ Non yellowing	IR Glass Bonding, Optical bonding, General purpose bonding of dis-similar substrates	Optically Clear	310	83 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	6
KU5147	Fast cure version of KU5144, Optimized for 365nm LED cure, low tack/ Excellent Adhesion to PET and Nylon and other plastic substrates	Battery Pouch Seal/ Sealing	Black	6100	58 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12



Product	Description	Typical Application	Color	Viscosity, P	lardness	Cure Condition	Shelf Life, months
KU5225	Excellent cure speed - 2 second cure/ Excellent Adhesion to PC, LCP and other plastics/ High Impact Performance	Encapsulation of components	Clear	4000	50D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12
KU5301	Exceptional adhesion to PC and other plastics/ Good Flexibility	Adhesive, Sealant	Clear	250	55 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12
KU5302	Exceptional adhesion to PC and other plastics/ Good Flexibility	Sealant or potting	Clear	5400	55 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12
KU5303	High Adhesion of difficult to bond to surfaces	Potting or encapsulation	Yellow	22000 - 28000	75 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12
KU5304	Very low Viscosity/ Tack Free/ Good adhesion to glass, PCB's and metal	Low Viscosity capillary flow UV	Clear	45	83 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12
KU5305	High adhesion to metals, plastics and glass/	Low Viscosity capillary flow UV	Clear	60	55 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12

PUR HOT MELT FOR ELECTRONIC DEVICE ENCLOSURE AND STRUCTURAL ASSEMBLY



Krylex high performance Reactive Polyurethane adhesives are formulated for the assembly of electronic portable devices and cure using atmospheric moisture. These reactive urethanes offer performance advantages over other adhesive technologies in enclosure and structural applications. The reactive urethanes are applied to the substrate via a heated dispense process, however the PUR cools rapidly when leaving the syringe so on contacting the target substrate the liquid adhesive is at, or close to, room temperature. The dispensed adhesive then develops rapid green strength for easy handling, prior to full moisture cure.

PUR Adhesives Offer:

- · One component
- · Almost instant bond strength.
- · A variety of open times to suit a wide variety of assembly requirements.
- · Exceptional Impact strength.
- · Ultra-low moisture uptake after cure.
- · Excellent chemical resistance.
- · Low dielectric constant
- · Excellent sealant properties
- · Excellent adhesion to a wide variety of plastics and metals
- · High Bio content.
- · ROHS Compliant

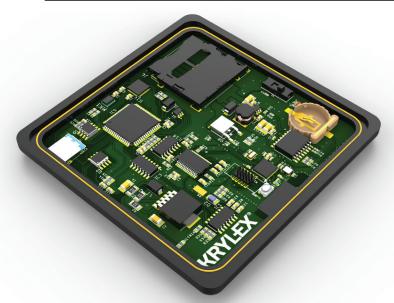




Product	Description	Typical Application	Dispense Temperature, ° C	Open Time, mins	Cure Time - Ambient Moisture , Hrs		Elongation at Break,
KH9001	Low MVTR/ High Reliability/ Low dielectric constant (2.1) and loss tangent (0.01) / Excellent Chemical Resistance/ High Bio content/ Dispensible PSA	Antenna bonding	120	10	72	73 A	>500
КН9005	Outstanding Barrier Sealant - Low MVTR/ High Reliability/ Low dielectric constant/ Excellent Chemical Resistance/ Low Bubble formation/ High Bio content/ Dispensible PSA	Barrier Sealant/ Encapsulant	120	2-4	72	71 A	>800
КН9005і	Outstanding Barrier Sealant - with Ultra low bondline bubble formation	Barrier Sealant/ Encapsulant					
КН106В	Excellent for bonding Metal to Plastic	Enclosure Bonding	105 -120	5 -10	24		>500
KH107	Very High Impact Performance/ Excellent Adhesion to plastics and metals/ Medium Green strength	High Impact applications bonding metals - Tablet Stylus	100 - 130	2-4	24	34D	>400
KH108B	Excellent Adhesion to metal and Plastic excellent Temperature and Chemical Resistance	Enclosure Bonding	100 - 130	5-10	24		>500
KH112B	Excellent Adhesion to metal and Plastic excellent Temperature and Chemical Resistance	Enclosure Bonding	100 - 130	5 -10	24		>500
KH168-1	Excellent Adhesion to metal and Plastic excellent Temperature and Chemical Resistance	Enclosure Bonding	100 - 130	5-10	24		>800
KH195	Excellent adhesion to metal and glass and fast cure	Enclosure Bonding	100 - 130	2-4	12	24D	>600
KH202	Excellent Adhesion to PC, PA and Metal, Easy Re-work	Enclosure Bonding	90 - 120	3	24		>600
KH813F	Excellent adhesion to plastics and metals/ Excellent solvent resistance/ Excellent Temperature cycle performance/ Low application temperature	Enclosure Bonding	90 -120	2 - 4	72	29 D	>500
KH911F	Excellent adhesion to plastics and metals/ Excellent solvent resistance/ Excellent Temperature cycle performance/ Low application temperature	Enclosure Bonding	90 -120	2	24	31 D	>450
KH936F	Excellent Adhesion to metal and Plastic excellent Temperature and Chemical Resistance	Enclosure Bonding - Cell Phone Back Cover	100 - 120	5- 10	24	24D	>500
KH946F	High Adhesion to glass, metal and plastic	Enclosure Bonding	95-125	4 -7	168	43D	>490
KH962F	Excellent Adhesion to PC, PA and Metal.	Enclosure - Cell Phone Touch Pane	l 95-125	2 - 4	24	33D	>600
КН965	Flexible / Medium Green Strength	Bonding Ferrite-PC-PI e.g. wireless charger assembly	100 -120	5	24	24D	>500







UV AND DUAL CURE ADHESIVES FOR ELECTRONIC COMPONENT ENCAPSULATION, SEALING AND CIRCUIT BOARD PROTECTION

Krylex range of adhesives for component encapsulation and circuit board protection provide industry leading environmental protection to ensure product reliability in ever more challenging application requirements in both consumer electronics and harsh automotive conditions.

Krylex UV + Moisture cure products offer high adhesion and a rapid, complete (no residual uncured adhesive) moisture cure after UV exposure

Encapsulation Adhesives Offer:

- · One component.
- · UV Cure and dual cure options (UV+ Moisture or UV + Thermal).
- · Ultra-fast UV Fixation.
- · High Reliability.
- · High UV depth of penetration.
- · Rapid moisture cure
- · Excellent Chemical Resistance.
- · Excellent waterproofing performance.
- · ROHS Compliant



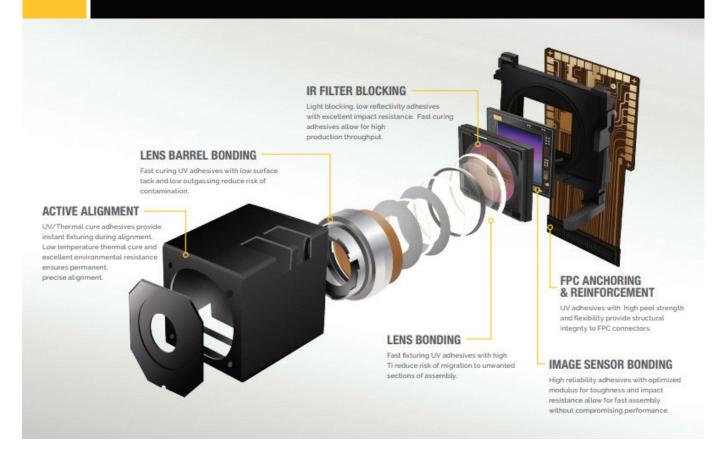


Product	Description	Typical Application	Color	Viscosity, H	ardness	Cure Condition	Shelf Life, months
		UV Encapsulation, Pot	ting and Sea	aling			
KU5301	Exceptional adhesion to PC and other plastics/ Good Flexibility	Adhesive, Sealant	Clear	200 - 300	55 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12
KU5302	Exceptional adhesion to PC and other plastics/ Good Flexibility	Sealant or potting	Clear	4800 - 6400	55 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12
KU5303	High Adhesion of difficult to bond to surfaces	Potting or encapsulation	Yellow	22000 - 28000	75 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12
KU5003	High adhesion to metals and plastics/ High Impact strength	Gap filling and sealing	Clear - Amber	160	44 D	365 -405nm LED 30 mW/cm2 , 2500 Mj	12
KU5003T	Thixotropic version of KU5003	Structural Bonding, Encapsulation	Clear - Amber	1000	44 D	365 -405nm LED 30 mW/cm2 , 2500 Mj	12
KU5225	Excellent cure speed - 2 second cure/Excellent Adhesion to PC, LCP and other plastics/ High Impact Performance	Encapsulation of components	Clear - Amber	4000	50D	365 -405nm LED 30 mW/cm2 , 2500 Mj	12
KU5045	Excellent Dispense/ Tack Free/ Good Adhesxion	Battery Pouch Seal/ Sealing	Black	7000	42 D	365 -405nm LED 30 mW/cm2 , 2500 Mj	6
	UV+	Moisture (Dual Cure) End	capsulants a	nd Sealants			
KD8010	Dual Cure CC (UV + Secondary moisture cure/ Exceptional depth of cure/ Opaque substrates possible	Encapsulation of temperature sensitive components where full UV Exposure is not possible	Clear	600	70D	365nm LED, 30mV cm2, 2500mJ + 24 Hour Moisture Cure	6
KD8011	Dual Cure CC (UV + Secondary moisture cure/ Exceptional depth of cure/ Opaque substrates possible	Encapsulation of temperature sensitive components where full UV Exposure is not possible	Translucen	t 2400	73 D	365nm LED, 30mV cm2, 2500mJ + 24 Hour Moisture Cure	6
KD5001	Very active Moisture cure, ideal if shadowing is high	Encapsulation of temperature sensitive components where full UV Exposure is not possible	Translucen	t 5400	55 D	365nm LED, 30mV cm2, 2500mJ + 24 Hour Moisture Cure	6





KRYLEX ADHESIVES FOR COMPACT CAMERA MODULES



Compact camera modules and image sensors used in today's portable consumer electronic devices and Automotive applications are constantly evolving as manufacturers try to differentiate their technology in this fast-moving industry. Krylex application specific camera module adhesives target high product performance, reliability and optimum manufacturing efficiencies.

KRYLEX® CCM Adhesives Offer:

- On component
- · Dual cure, UV + Thermal, for Active Alignment Applications.
- · UIV Command cure.
- High adhesion to glass, metals, and a wide variety of plastics (LCP, PC, PBT,etc.)
- · Optimised rheology, high shape stability etc...
- · High Reliability









KRYLEX ADHESIVES FOR WEARABLE APPLICATIONS



KRYLEX® Wearable Adhesives Solutions Offer:

- · One component.
- · UV Cure and dual cure options (UV+ Moisture or UV + Thermal).
- · Ultra-fast UV Fixation.
- · High Reliability.
- · High UV depth of penetration.
- · Rapid moisture cure
- · Reactive Polyurethanes that cure in the presence of atmospheric moisture
- $\cdot \ \, \text{Excellent waterproofing and environmental stability performance}.$
- · ROHS CompliantOne component.





		Typical		Viscosity		Cure	Shelf Life,
Product	Description	Application	Color	Viscosity, CPS	Hardness	Condition	months
		Sealing and E	incapsulation				
KD8010	Dual Cure CC (UV + Secondary moisture cure/ Exceptional depth of cure/ Opaque substrates possible	Low Viscosity UV + Moisture	Clear	600	70 D 3	365nm LED, 30mW/cm2, 2500m 24 Hour Moisture C	J 12 Jure
KU5301	Exceptional adhesion to PC and other plastics/ Good Flexibility	Adhesive, Sealant	Clear	200 - 300	55 D	30 sec @ 10 mW/ cm2 @ 365 nm	12
KU5303	High Adhesion of difficult to bond to surfaces	Potting or encapsulation	Yellow	22000 - 28000	75 D	30 sec @ 10 mW/ cm2 @ 365 nm	12
KU5225	Excellent cure speed - 2 second cure/Excellent Adhesion to PC and other plastics/ High Impact Performance	Encapsulation of components	Clear - Amber	4000	50 D	365 -405nm LED 30 mW/ cm2 , 2500 Mj	12
KU5045	Fast cure, low shrinkage, Tack Free/ Good Adhesion to plastic substrates, metals and glass	Battery Pouch Seal/ Sealing	Black	7000	42D	365 -405nm LED 30 mW/ cm2 , 2500 Mj	12
KD8010	Dual Cure CC (UV + Secondary moisture cure/ Exceptional depth of cure/ Opaque substrates possible	Encapsulation of temperature sensitive components where full UV Exposure is not possible	Clear	600		365nm LED, 30mW/cm2, 2500m 24 Hour Moisture C	
KD8011	Dual Cure CC (UV + Secondary moisture cure/ Exceptional depth of cure/ Opaque substrates possible	Encapsulation of temperature sensitive components where full UV Exposure is not possible	Translucent	2400		365nm LED, 30mW/cm2, 2500m 24 Hour Moisture C	
KD5001	Very active Moisture cure, ideal if shadowing is high	Encapsulation of temperature sensitive components where full UV Exposure is not possible	Translucent	5400		365nm LED, 30mW/cm2, 2500m 24 Hour Moisture C	
	Weara	ble Display Adhesiv	es for FPC Rei	nforcement			
KU5016	High Peel strength for flexible substrates/ Excellent adhesion to PA and PET / Tack free	FPC Adhesive	Clear - Amber	4500	68 D	72 Hours	1 Year @ 25 ∘ C
KU5023	Higher strength than 5016 - not tack free	FPC Adhesive	Clear - Amber	15000	70 D	72 Hours	1 Year @ 25 ∘ C





	Display Barrier Sealant (PUR Hot Melt)								
Product	Description	Typical Application	Dispense Temperature,	Open Time, mins	Cure Time - Ambient Moisture, hrs	Hardness	Elongation at Break %		
КН9005	Outstanding Barrier Sealant - Low MVTR/ High Reliability/ Low dielectric constant/ Excellent Chemical Resistance/ Low Bubble formation/ High Bio content	Barrier Sealant	120	10 - 20	24	71 A	>800		
	Adhesiv	es for Wearable	e Enclosure Bondi	ng (PUR Hot Me	elt)				
KH9001	Low MVTR/ High Reliability/ Low dielectric constant/ Excellent Chemical Resistance/ High Bio content	Antenna bonding	120	10	24	73 A	>500		
КН9005	Outstanding Barrier Sealant - Low MVTR/ High Reliability/ Low dielectric constant/ Excellent Chemical Resistance/ Low Bubble formation/ High Bio content	Barrier Sealant	120	10 - 20	24	71 A	>800		
KH813F	Excellent adhesion to plastics and metals/ Excellent solvent resistance/ Excellent Temperature cycle performance/ Low application temperature	Enclosure Bonding	90 - 120	2-4	72	29 D	>500		
KH911F	Excellent adhesion to plastics and metals/ Excellent solvent resistance/ Excellent Temperature cycle performance/ Low application temperature	Enclosure Bonding	90 - 120	2	24	31 D	>450		





KRYLEX ADHESIVES FOR THE ASSEMBLY OF ACOUSTIC MODULES, MICRO SPEAKERS AND EARPHONES



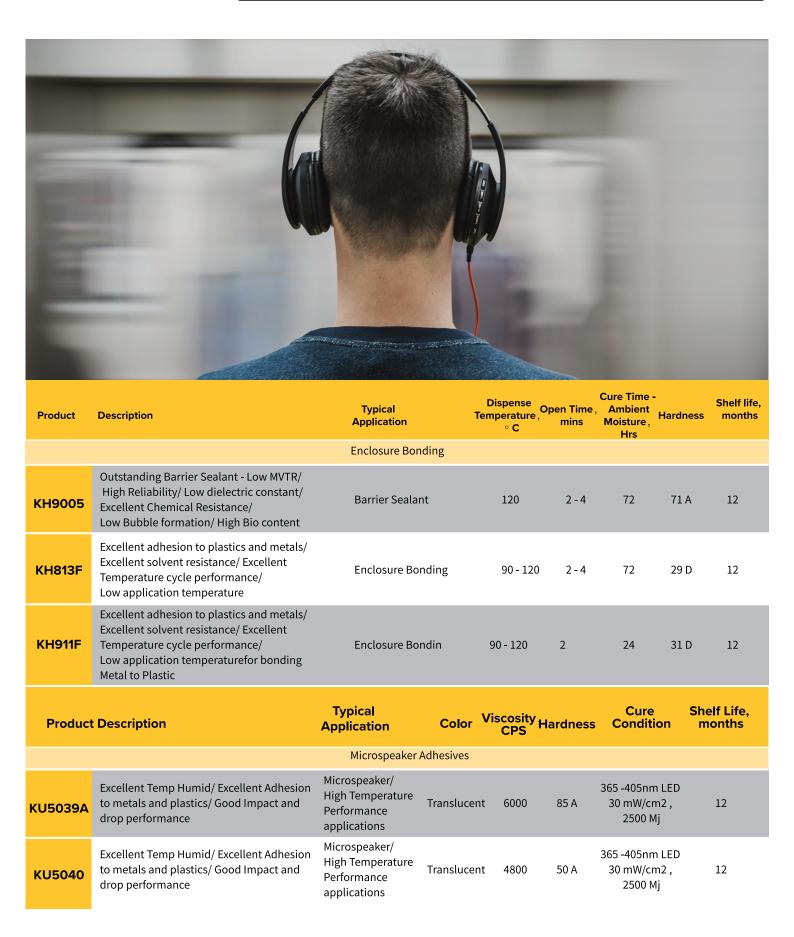
Krylex adhesives provide a wide range of different assembly options in construction of speakers, headphones, acoustic modules and micro speakers. The products provide customers with optimised properties that aid in the assembly and final reliability of the assembled device.

Adhesives for Acoustic Applications Offer:

- · Excellent, fine pitch dispense performance.
- · High Reliability.
- · High Temperature Resistant for micro speaker bonding.
- · Excellent adhesion to difficult to bond plastics and anodised Al.
- · ROHS Compliant.
- · Exceptional Impact strength for enclosure applications











Product	Description	Color	Viscosity,	Thixotropi	c	Cure	Wo	rk Ilfe Sh	elf Life @ -20℃,
rioduct	Description	COIOI	cps	Index		Schedule	***	ik ilie	months
			Magnet Bo	nding - Therm	ıal Curii	ng			
KE1092	High Adhesion to difficult bond to plastics e.g. PC	to Biege	3800	2.93		iins at 100 ° C c iins at 80 ° C	r 81	Hours	12
KE1094	High Adhesion to plastics and metals/ High Tg and low CTE	Dark Grey	80000	5.9	80	∘ C for 30 mins	24 hou	rs at 25 ∘ C	12
KE1095	High Adhesion to plastics and metals/ High Tg and low CTE	Dark Grey	52000	6.3	80	∘ C for 30 mins	24 hou	rs at 25 ∘ C	12
Product	Description	Typical Application		Dispense Temperature ° C	,	Open Time, mins	Cure Ti Ambi Moistu Hrs	ent Ire, Hardne	Shelf Life, Productths
			Magnet Bond	ling - PUR - Mo	oisture (Cure			
KH965F	Flexible / Medium Green Strength	Bonding Ferrit PC-PI e.g. wire charger Assem	less !	5000 cps @120) ∘ C		24 Hrs at	25 ∘ C 24 I	O 12
Product	Description		Typica	al				•	Chalf I ifa
	Description		Applica		olor	Viscosity, H	ardness	Cure Condition	Shelf Life, n months
	Description		Applica			Viscosity, H	ardness		
KU5016	High Peel strength for flex Excellent adhesion to PA a Tack free		Applica FPC Flexible sonding	E Reinforcements Substrate - High e bonds -		Viscosity, H CPS 4500	ardness 68 D		months ED
KU5016	High Peel strength for flex Excellent adhesion to PA a	and PET /	Flexible s bonding Peel forc wire fixin circuit Flexible s bonding	Reinforcements Substrate - High e bonds - A substrate - High e High c A	nt lear -			Condition 365 -405nm L 30 mW/cm2	ED 12
	High Peel strength for flex Excellent adhesion to PA a Tack free Higher peel strength than	and PET /	FPC Flexible so bonding Peel force wire fixing circuit Flexible so bonding Peel force wire fixing Peel force wire fixing Peel force wire fixing fixed	E Reinforcement substrate - High Cape, flex A substrate - High Cape, flex A substrate - High Cape, flex A flit Cape and the substrate cap	nt lear - mber lear -	4500	68 D 70 D	365 -405nm L 30 mW/cm2 2500 Mj 365 -405nm L 30 mW/cm2	ED 12 ED , 12 Shelf Life,
KU5023	High Peel strength for flex Excellent adhesion to PA a Tack free Higher peel strength than low shrinkage	and PET /	Flexible sonding Peel forcuit Flexible sonding Peel forcuit Flexible sonding Peel forcuit Flexible sonding Peel forcuit flex circuit	E Reinforcement substrate - High Cape, flex A substrate - High Cape, flex A substrate - High Cape, flex A flit Cape and the substrate cap	lear - mber lear - mber	4500 1500	68 D 70 D	365 -405nm L 30 mW/cm2 2500 Mj 365 -405nm L 30 mW/cm2 2500 Mj	ED 12 ED , 12 Shelf Life,
KU5023	High Peel strength for flex Excellent adhesion to PA a Tack free Higher peel strength than low shrinkage	5016 , tacky,	Flexible sonding Peel forcuit Flexible sonding Peel forcuit Flexible sonding Peel forcuit Flexible sonding Peel forcuit flex circuit	Reinforcements Substrate - High e bonds - ng, flex Substrate - High e bonds - A substrate - High e bonds - A c Reinforcements C Reinforcements	lear - mber lear - mber	4500 1500	68 D 70 D	365 -405nm L 30 mW/cm2 2500 Mj 365 -405nm L 30 mW/cm2 2500 Mj	ED 12 Shelf Life, months







Digital Display technology is a rapidly evolving area for today's electronics devices manufacturers. The display quality and performance are the most obvious and instant impression that a consumer will have when using an electronic device. It is therefore critical that Electronic Display manufacturers can drive display innovation forward to differentiate their product to the consumer. The use of high performance, robust materials in the construction of the display ensures that reliability and functionality are optimum. Krylex adhesives enable Display manufacturers to achieve these performance goals.

RYLEX® Display Adhesives Offer:

- · One component.
- · UV Cure and dual cure options (UV+ Moisture or UV + Thermal).
- · Ultra-fast UV Fixation.
- · High Reliability.
- · High UV depth of penetration.
- · Rapid moisture cure
- · Excellent Chemical Resistance.
- $\cdot \ \, \text{Excellent waterproofing performance}.$
- · ROHS Compliant





Product	Description		Typical Application	Color	Viscosity, CPS	Hardness	Cure Condition	Shelf Life, months
			Display F	Panel Adhesives				
KU5026	Excellent cure speed - 2 second Excellent Adhesion to PC and o plastics/ High Impact Performa	ther	Display End Se	clear - Amber	9800	55 D	365 -405nm LED 30 mW/cm2 , 2500 Mj	12
KD8011	Dual Cure CC (UV + Secondary moisture cure/ Exceptional dep cure/ Opaque substrates possil		Display Pin Sea	al Transluce	nt 2400	36 73 D	5nm LED, 30mW/c 2500mJ + 24 Hou Moisture Cure	
KD5001	Very active Moisture cure, idea shadowing is high	l if	Display Pin Sea	al Transluce	nt 5400	36 55 D	5nm LED, 30mW/c 2500mJ + 24 Hou Moisture Cure	
KU5225	Excellent cure speed - 2 second Excellent Adhesion to PC and o plastics/ High Impact Performa	ther	Display Pin Sea	al Clear - Amber	4000	50 D	365 -405nm LED 30 mW/cm2 , 2500 Mj	12
KU5016	High Peel strength for flexible substrates/ Excellent adhesion PET and glass/ Tack free	to PA,	FPC Reinforcer	ment Clear - Amber	4500	68 D	365 -405nm LED 30 mW/cm2 , 2500 Mj	12
KU5303	High Adhesion of difficult to bo to surfaces	ond	FPC Reinforcer	ment Yellow	22000 - 2800	0 75 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12
Product	Description		ypical	Dispense Temperature,	Open Time	Cure Tir		Elongation
		Арі	plication	° C	mins	Moistur Hrs	re, Hardness	at Break, %
		Арі	plication	• /	mins	Moistu	re, Hardness	
КН9005	Outstanding Barrier Sealant - Low MVTR/ High Reliability/ Low dielectric constant/ Excellent Chemical Resistance/ Low Bubble formation/ High Bio content	Rarri	plication	• c	mins	Moistu	re, Hardness	
KH9005	Low MVTR/ High Reliability/ Low dielectric constant/ Excellent Chemical Resistance/ Low Bubble formation/	, Barri	Display Fu Display Fu er Sealant	o Cunctional Sealant	mins	Moistur Hrs	71 A	%
	Low MVTR/ High Reliability/ Low dielectric constant/ Excellent Chemical Resistance/ Low Bubble formation/ High Bio content	, Barri	Display Further Sealant Viscosity, Tops	unctional Sealant 120 ° C	2-4 Cure Schedule	Moistur Hrs	71 A	>400
	Low MVTR/ High Reliability/ Low dielectric constant/ Excellent Chemical Resistance/ Low Bubble formation/ High Bio content	, Barri	Display Further Sealant Viscosity, Tops	unctional Sealant 120 ° C Thixotropic Index ing - Thermal Cu	2-4 Cure Schedule	Moistur Hrs	71 A	>400
Product	Low MVTR/ High Reliability/ Low dielectric constant/ Excellent Chemical Resistance/ Low Bubble formation/ High Bio content Description High Adhesion to difficult to bond to plastics e.g. PC High Adhesion to plastics	. Barri Color	Display Further Sealant Viscosity, Tops Magnet Bond 3800	120 ° C Thixotropic Index ing - Thermal Cu 2.93 mi	Cure Schedule	Woods a series of the series o	71 A Prk IIfe Hours 1	% >400 Shelf Life
Product KE1092	Low MVTR/ High Reliability/ Low dielectric constant/ Excellent Chemical Resistance/ Low Bubble formation/ High Bio content Description High Adhesion to difficult to bond to plastics e.g. PC High Adhesion to plastics and metals/ High Tg and low CTE High Adhesion to plastics	. Barri Color Biege	Display Further Sealant Viscosity, Tops Magnet Bond 3800	120 ° C Thixotropic Index ing - Thermal Cu 2.93 mi 5.9 86	Cure Schedule ring min at 100 ° C ons at 80 ° C	Woods as 24 hou	71 A Prk IIfe Hours 1 rs at 25 ° C 1	% >400 Shelf Life Year @ -20 ° c





KRYLEX ADHESIVE SOLUTION FOR ELECTRONIC DEVICE WATERPROOFING



As electronic devices have become more mobile the requirements around the number of distinct environments a device will see have increased. Specifically, mobile phones and electronic wearable devices are now required to offer higher levels of waterproof performance so that they can remain with the user throughout the day irrespective of whether walking, running, or swimming. Krylex performance adhesives offer customers a range of product types used in sealing and encapsulation of components and devices to meet these now everyday environmental challenges.

KRYLEX Waterproof Adhesives Solutions Offer:

- · One component.
- · UV Cure and dual cure options (UV+ Moisture or UV + Thermal).
- · Ultra-fast UV Fixation.
- · High Reliability.
- · High UV depth of penetration.
- · Rapid moisture cure
- · Reactive Polyurethanes that cure in the presence of atmospheric moisture
- · Excellent waterproofing performance.
- · ROHS Compliant





Product	Description	Typical - Application	Dispense [emperature ○ C	Open Time , mins	Cure Tin Ambie Moistui Hrs	nt Hardness	Elongation at Break, %
		S	ealing				
КН9005	Outstanding Barrier Sealant - Low MVTR/ High Reliability/ Low dielectric constant/ Excellent Chemical Resistance/ Low Bubble formation/ High Bio content	Barrier Sealant	120	2 to 4	72	71 A	>400
KH813F	Excellent adhesion to plastics and metals/ Excellent solvent resistance/ Excellent Temperature cycle performance/ Low application temperature	Enclosure Bonding	90-120	2 to 4	72	29 D	>500
KH911F	Excellent adhesion to plastics and metals/ Excellent solvent resistance/ Excellent Temperature cycle performance/ Low application temperature	Enclosure Bonding	90-120	2	24	31 D	>450
Product	Description	Typical Application	Color	Viscosity, P	-lardness	Cure Condition	Shelf Life, months
		Component and S	elective Encaps	ulation			
KD8011	Dual Cure CC (UV + Secondary moisture cure/ Exceptional depth of cure/ Opaque substrates possible	Encapsulation of temperature sensitive components where full UV Exposure is not possible	Translucent	2400	73 D	365nm LED, 30mW/cı 2500mJ + 24 Hour Moisture Cure	
KD5001	Very active Moisture cure,	Encapsulation of temperature sensitive	Translucent	5400	55 D	865nm LED, 30mW/ci 2500mJ + 24 Hour	
KD5001	ideal if shadowing is high	components where full UV Exposure is not possible	Hanstacent	3400	33 B	Moisture Cure	
KU5304	ideal if shadowing is high Very low Viscosity/ Tack Free/ Good adhesion to glass, PCB's and metal	full UV Exposure is	Clear	40 - 50	83 D		12



KRYLEX ADHESIVES FOR BATTERY POUCH SEAL



With the growth in mobile devices and the onset of electric Vehicles (EV) Battery development is moving rapidly. Battery manufacturers are looking at ways to increase performance while reducing weight and battery footprint. Krylex adhesives for battery/cell construction offer customers optimised performance depending on the applications that are focussed on delivering the current and next level requirements for the industry.

KRYLEX® Battery Adhesives Offer:

- · One component.
- · UV Cure
- · Ultra-fast UV Fixation.
- · High Reliability.
- · High UV depth of penetration.

Product	Description	Typical Application	Color	Viscosity, CPS	Hardness	Cure Condition	Shelf Life, months
		Battery Pouch S	eal Adhesive	es			
KU5144	Tack Free/ Excellent Adhesion to PET and Nylon and other plastic substrates	Battery Pouch Seal/ Sealing	Black	7000	54 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12
KU5145	Clear version of KU5144	Battery Pouch Seal/ Sealing	Yellow	7400	51 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12
KU5147	Increased cure speed version of KU5144, Optimized for 365nm LED cure, Tack Free/ Excellent Adhesion to PET and Nylon and other plastic substrates	Battery Pouch Seal/ Sealing	Black	6100	58 D	365 -405nm LED 30 mW/cm2 , 2500 mJ	12





Krylex low temperature, thermal cure solutions offer customers excellent adhesive strength and high reliability at cure temperatures compatible with the low temperature stability plastics and anodised metal surfaces used in the assembly of electronic devices.

KRYLEX°

Low Temp Thermal Cure Adhesive Offer:

- · One component.
- · High structural strength
- · Cure capability in the range 60 80 °C
- · Excellent Adhesion to plastics and metal (various types and grades).
- · High Reliability.
- · Low solvent content (prevent damage to substrate surfaces)
- · Flexible and able to tolerate CTE Mismatch.
- · ROHS Compliant.

Product	Description	Color	Viscosity, cps	Thixotropic Index	Cure Schedule	Work life	Shelf Life @ -20 °C, months
		Low	Temperature	Thermal Cure	Epoxy Adhesive		
KE1092	High Adhesion to difficult to bond to plastics e.g. PC	Biege	3800	2.93	30 mins at 100 ° C or 60 mins at 80 ° C	8 Hours	12
KE1093	High Performance LTC	Black	10000	4	5 - 10 mins at 80 ° C	21 days at 25 ° (C 12
KE1094	High Adhesion to plastics and metals/ High Tg and low CTE	Dark Grey	80000	5.9	80 ° C for 30 mins	24 hours at 25 ∘	C 12
KE1095	High Adhesion to plastics and metals/ High Tg and low CTE	Dark Grey	52000	6.3	80 ∘ C for 30 mins	24 hours at 25 ∘	C 12
KE1096	Exceptional adhesion to steel, stainless steel, aluminum, plastics, glass, etc.	Off White	25000		30 mins at 125 ∘ C	25 hours at 25 ∘ C	12





KRYLEX CYANOACRYLATE ADHESIVES FOR ELECTRONIC APPLICATIONS

Krylex Toughened Cyanoacrylate (CA) Technology is offering customers a forward step in the kinds of reliability performance that CA'S can achieve in the electronics market.

KRYLEX® CA Solutions Offer:

- · One component.
- · 'Instant' Cure
- · Excellent impact strength.

Product	Description	Typical Applications	Color	Impact Strength, modified charpy, j/cm2
KB5002	High Impact Strength, Cyanoacrylate Adhesive	Speaker/ Headphone / Sensor fixturing	Opaque	12.6







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